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(19) **United States**(12) **Patent Application Publication**
CHIU(10) **Pub. No.: US 2022/0361368 A1**(43) **Pub. Date: Nov. 10, 2022**(54) **LIQUID COOLING LOOP HEAT
DISSIPATING DEVICE AND HEAT
DISSIPATING SYSTEM THEREOF**(52) **U.S. Cl.**
CPC **H05K 7/20272** (2013.01); **H05K 7/20927**
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H05K 7/20 (2006.01)(57) **ABSTRACT**

A heat dissipating device includes a power distribution assembly and two convergence delivery assemblies. The power distribution assembly includes a first cooling reservoir, a second cooling reservoir, multiple cooling pumps disposed on the first cooling reservoir, and a serial pipeline and a cooling head corresponding to each of the cooling pumps respectively. The two convergence delivery assemblies separately communicate with first cooling reservoir and the second cooling reservoir, and are separately arranged on two sides of the power distribution assembly. The serial pipeline is connected with the cooling head to communicate between the first cooling reservoir and the second cooling reservoir.

